



Mechanical Data

Case: U-DFN2510-10

4 CHANNELS LOW CAPACITANCE TVS DIODE ARRAY

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: NiPdAu over Copper Leadframe (Lead Free Plating).

UL Flammability Classification Rating 94V-0

Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.038 grams (Approximate)

Solderable per MIL-STD-202, Method 208 (e4)

Features & Applications

- Clamping Voltage: 9V at 10A 100ns, TLP 9.4V at 5.5A 8µs/20µs
- IEC 61000-4-2 (ESD): Air ±16kV, Contact ±14kV
- IEC 61000-4-4 (EFT): Level 4
- IEC 61000-4-5 (Lightning): ±5.5A (8/20µs)
- 4 Channels of ESD Protection

Pin#

1, 2, 4, 5

6, 7, 9, 10

3, 8

- Low Channel Input Capacitance of 0.55pF Typical
- TLP Dynamic Resistance: 0.25Ω
- Typically Used for High Speed Ports such as USB 2.0, USB 3.0 DVI™, HDMI2.0, Ethernet Port, IEEE, MDDI, PCI Express[®], SATA/ eSATA
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen, Antimony and Beryllium Free. "Green" Device (Note 3)

Description

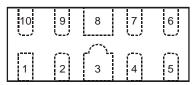
I/O

No Connection

Vss

 An Automotive-Compliant Part is Available Under Separate Datasheet (DT1240-04LPQ)

U-DFN2510-10 and U-DFN2510-10 (Type CJ)





Pin Description (Top View)

Device Schematic

2

Pin 5

Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1240-04LP-7	Standard	BC7	7	8	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information

BC7 YM

BC7 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: G = 2019) M = Month (ex: 9 = September)

BC7 YWX

BC7 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 9 = 2019)

W = Week

(ex: a=Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U=Monday)

Date Code Key for YM

Year	20	19	20	20	20	21	20	22	20	23	20	24
Code	(3	ŀ	+			,	J	ŀ	(L	-
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Date Code Key for VWX

Year	2019	2020	2021	2022	2023	2024	2025
Code	9	0	1	2	3	4	5
Week	1	-26	27	-52	5		
Code	,	∖-Z	а	-Z	Z	<u>'</u>	1
		•					•

 Internal Code
 Sun
 Mon
 Tue
 Wed
 Thu
 Fri
 Sat

 Code
 T
 U
 V
 W
 X
 Y
 Z

PCI Express is a trademark or registered trademark of PCI-SIG.



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I _{PP}	5.5	Α	I/O to V _{SS} , 8/20µs
Peak Pulse Power, per IEC 61000-4-5	P_{PP}	60	W	I/O to V _{SS} , 8/20µs
Operating Voltage (DC)	V_{DC}	6	V	I/O to V _{SS}
ESD Protection – Contact Discharge, per IEC 61000-4-2	V _{ESD_CONTACT}	±14	kV	I/O to V _{SS}
ESD Protection – Air Discharge, per IEC 61000-4-2	V_{ESD_AIR}	±16	kV	I/O to V _{SS}
Operating Temperature	T _{OP}	-55 to +85	°C	_
Storage Temperature	T _{STG}	-55 to +150	°C	_

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P _D	350	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{ hetaJA}$	360	°C/W

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	_	_	5.5	V	I _R =1mA, I/O to V _{SS}
Reverse Current	I _R	_	_	0.5	μA	$V_R = 5V$, I/O to V_{SS}
Reverse Breakdown Voltage	V_{BR}	6	_	_	V	I _R = 1mA, I/O to V _{SS}
Forward Clamping Voltage	V _F	-1.0	-0.85	_	V	$I_F = -15 \text{mA}$, I/O to V_{SS}
Holding Voltage	VH	5.5	_	_	V	_
Reverse Clamping Voltage (Note 6)	Vc	_	9.4	11	V	$I_{PP} = 5.5A$, I/O to V_{SS} , 8/20 μ s
Trigger Voltage	V _{TRIG}	_	_	9.5	V	_
ESD Clamping Voltage	V _{ESD}	_	9	_	V	TLP, 10A, t_P = 100ns, I/O to V_{SS}
Dynamic Reverse Resistance	R _{DIF-R}	_	0.25	_	Ω	TLP, 10A, t_P = 100ns, I/O to V_{SS}
Dynamic Forward Resistance	R _{DIF-F}	_	0.25	_	Ω	TLP, 10A, t _P = 100ns, V _{SS} to I/O
Channel Input Capacitance (Note 7)	C _{I/O}	-	0.55	0.65	pF	$V_{I/O} = 2.5V$, $V_{SS} = 0V$, $f = 1MHz$
Delta C _{I/O}	C _{I/OMAX} -C _{I/OMIN}	1	0.04	_	pF	C _{I/OMAX} -C _{I/OMIN}

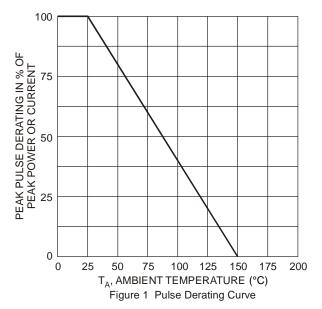
Notes:

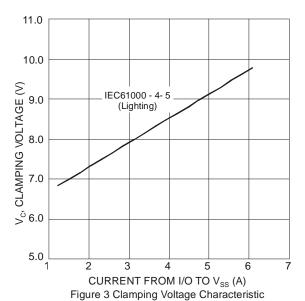
^{5.} Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at http://www.diodes.com/package-outlines.html.

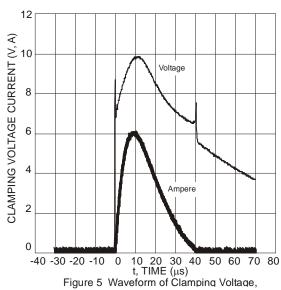
^{6.} Clamping voltage value is based on an $8x20\mu s$ peak pulse current (I_{pp}) waveform.

 $^{7.\} C_{I/O1} = C_{PIN1} + C_{PIN10},\ C_{I/O2} = C_{PIN2} + C_{PIN9},\ C_{I/O3} = C_{PIN4} + C_{PIN7},\ C_{I/O4} = C_{PIN5} + C_{PIN6}$

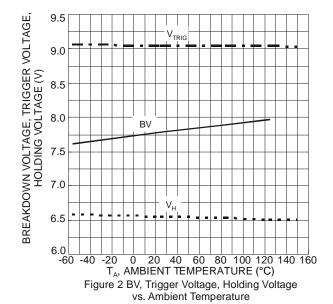


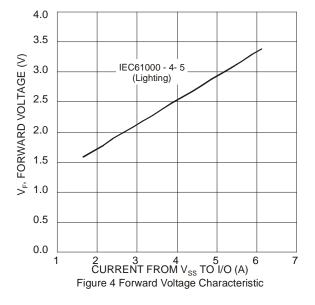


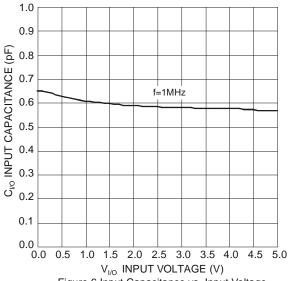




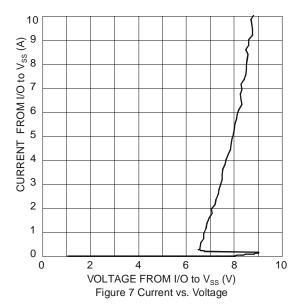
Current vs.Time (8/20µs, I/O to V_{SS})







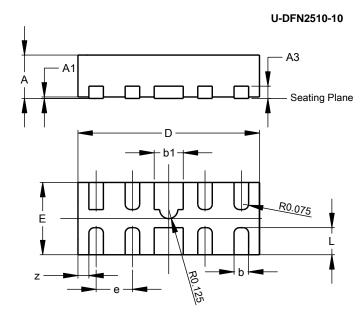






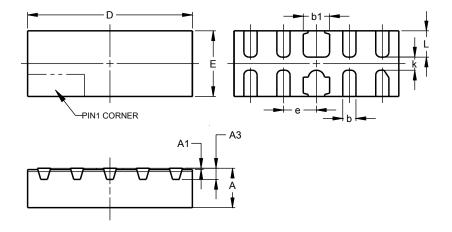
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Ų	U-DFN2510-10					
Dim	Min	Max	Тур			
Α	0.545	0.605	0.575			
A1	0.00	0.05	0.03			
А3	-	-	0.13			
b	0.15	0.25	0.20			
b1	0.35	0.45	0.40			
D	2.450	2.575	2.500			
е	-	-	0.50			
Е	0.950	1.075	1.000			
Ĺ	0.325	0.425	0.375			
Z	-	-	0.150			
All D	All Dimensions in mm					

U-DFN2510-10 (Type CJ)



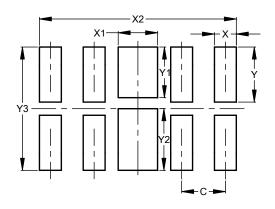
U-DFN2510-10					
	(Type	CJ)			
Dim	Min	Max	Тур		
Α	0.545	0.605			
A1	0.00	0.05			
А3	0.152REF				
b	0.150	0.250			
b1	0.350	0.450			
D	2.450	2.575			
Е	0.950	1.075			
е			0.500		
Е	0.950	1.075	1.000		
L	0.350 0.450				
k	0.200REF				
All D	imensi	ons in	mm		



Suggested Pad Layout

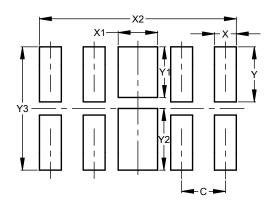
Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2510-10



Dimensions	Value (in mm)
С	0.500
X	0.250
X1	0.450
X2	2.250
Υ	0.625
Y1	0.575
Y2	0.700
Y3	1.400

U-DFN2510-10 (Type CJ)



Dimensions	Value
פווטופווזטווט	(in mm)
C	0.500
Х	0.250
X1	0.450
X2	2.250
Y	0.625
Y1	0.575
Y2	0.700
V3	1 400



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